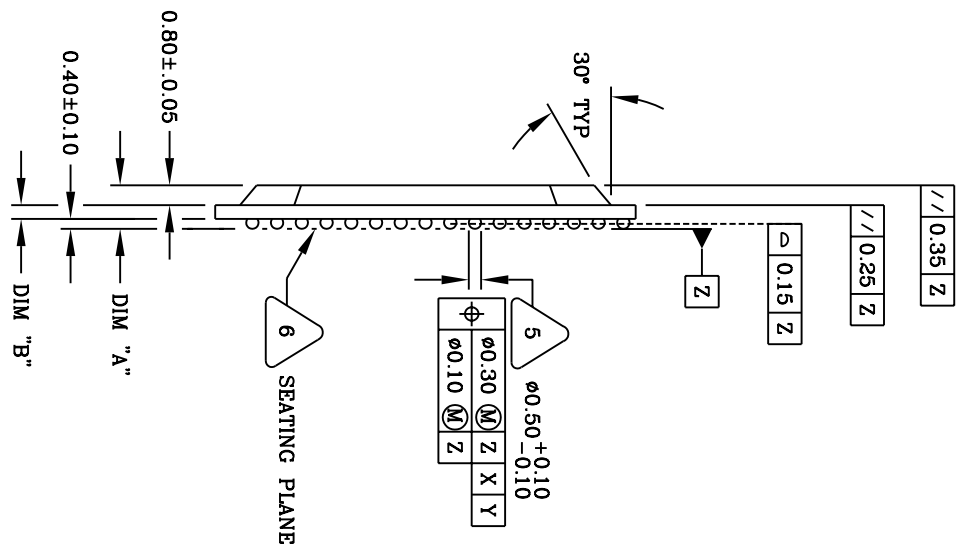
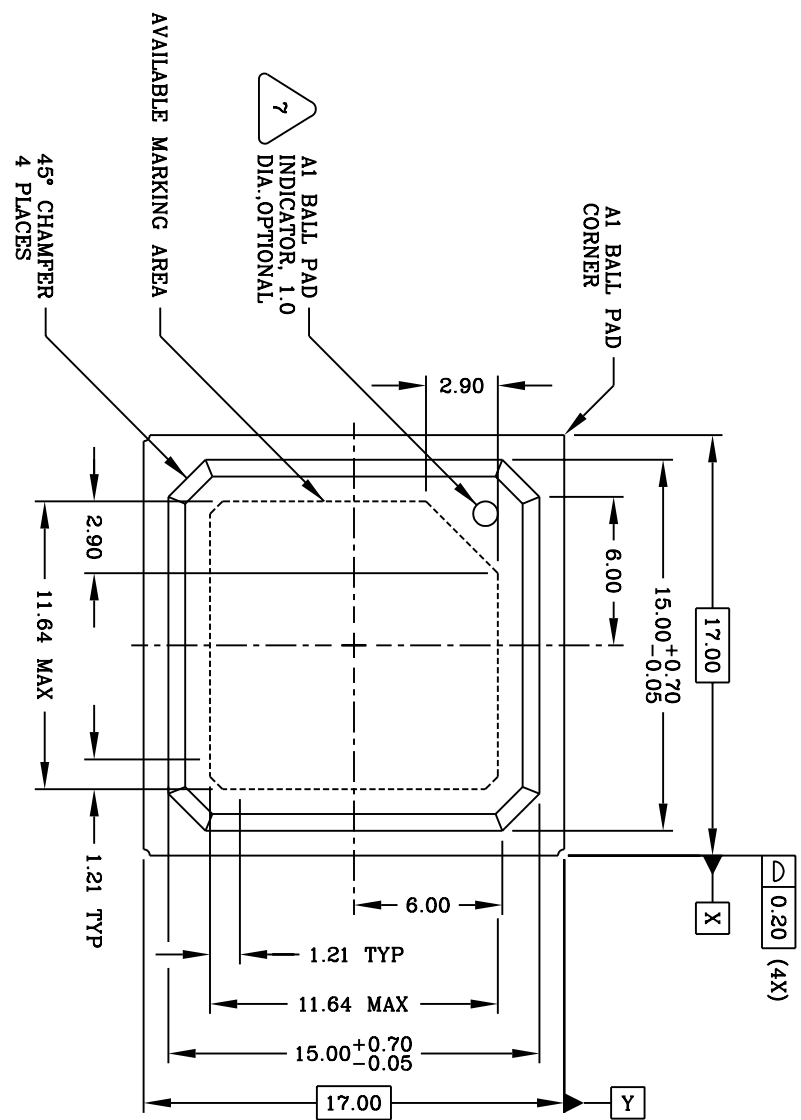


REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
	01	ADD "GREEN" BPG NOMENCLATURE	10/20/04	TU VU



**SIDE VIEW**

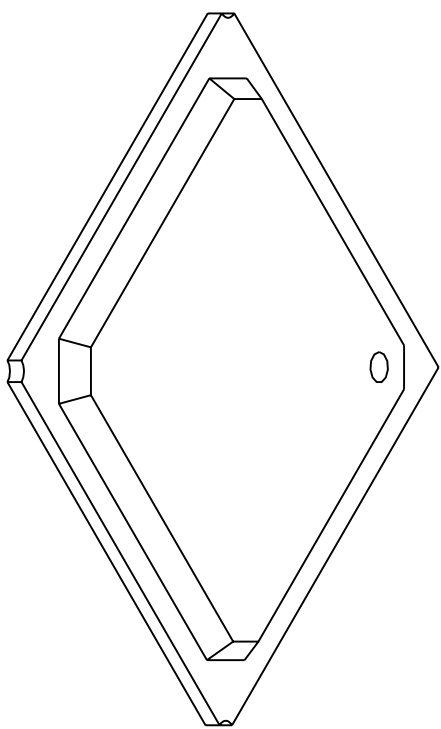
PBGA THICKNESS SCHEDULE			
NO. LAYERS	DIM "A"	DIM "B"	
2	1.56 <sup>+0.19</sup> <sub>-0.21</sub>	0.36 <sup>+0.04</sup> <sub>-0.06</sub>	
4	1.76 <sup>+0.21</sup>	0.56 <sup>+0.06</sup>	



**TOP VIEW**

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS ANGULAR IT		Integrated Device Technology, Inc. 2975 Slender Way, Santa Clara, CA 95054 www.IDT.com (408) 727-6116 FAX (408) 492-8074
APPROVALS DRAWN <i>PKP</i> CHECKED	DATE 10/23/00	
TITLE: BB/BBG 208 PACKAGE OUTLINE 17.0 X 17.0 mm BODY PBGA		
DRAWING No. PSC-4097		SIZE C
DO NOT SCALE DRAWING		SCALE N/A
SHEET 1 OF 3		REV 01

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
01	01	ADD "GREEN" BBG NOMENCLATURE	10/20/04	TU VU



NOTES: UNLESS OTHERWISE SPECIFIED

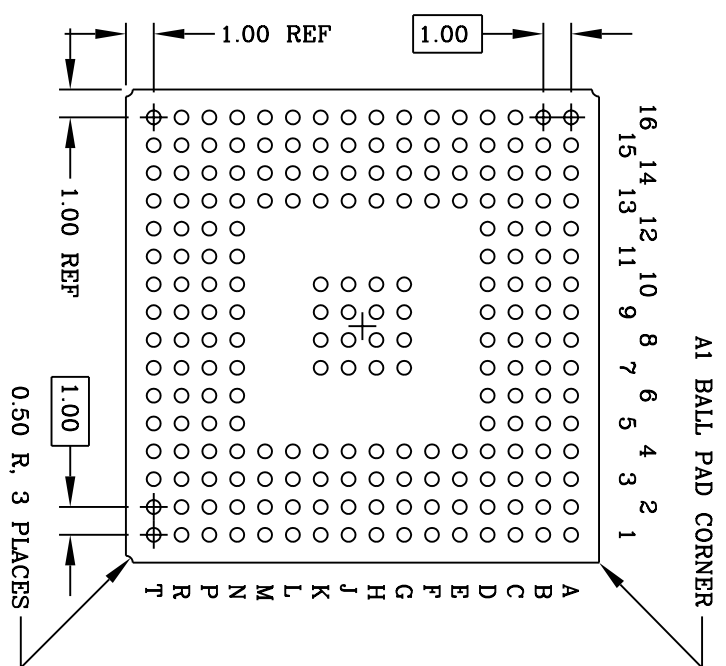
- ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.
- THE BASIC SOLDER BALL GRID PITCH IS 1.00mm.
- THE MAXIMUM SOLDER BALL MATRIX SIZE IS 16 X 16.
- REFERENCE SPECIFICATIONS:
  - A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
  - B. AAWW SPEC #001-0519-2062: MARKING.
  - C. THIS DRAWING CONFORMS TO THE JEDEC REGISTERED OUTLINE MO-151/C, VARIATION AAF-1 EXCEPT FOR aaa, b, AND A1 DIMENSIONS.

JEDEC(AMKOR) DIM	MIN	NOM	MAX
aaa	0.20(0.15)	0.50(0.40)	0.60(0.50)
A1	0.40(0.30)	0.50(0.40)	0.60(0.50)
b	0.50(0.40)	0.60(0.50)	0.70(0.60)

DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.

PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

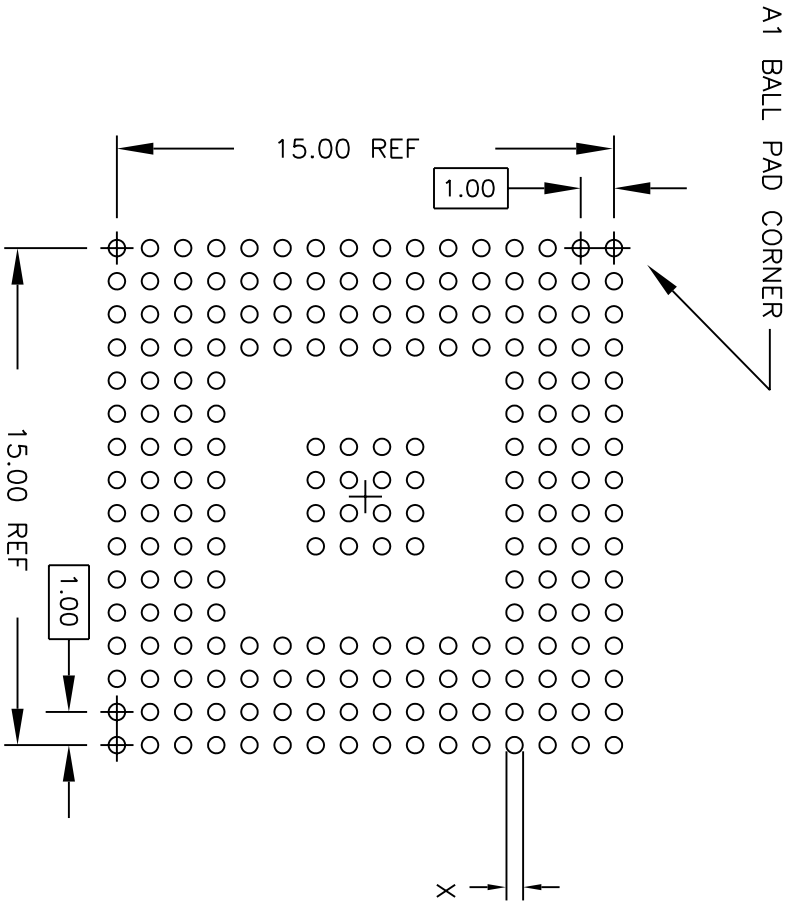
A1 BALL PAD CORNER I.D. FOR PLATE MOLD: TO BE MARKED BY INK. AUTO MOLD: DIMPLE TO BE FORMED BY MOLD CAP.



**BOTTOM VIEW**  
(208 SOLDER BALLS)

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS AND IN ANGULAR DEGREES		 Integrated Device Technology, Inc. 2975 Stender Way, Santa Clara, CA 95054 (408) 727-6116 FAX (408) 492-8074	
APPROVALS	DATE	TITLE:	
DRAWN: p3/p	10/23/00	BB/BBG 208 PACKAGE OUTLINE	
CHECKED:		17.0 X 17.0 mm BODY PBGA	
		DRAWING No.	PSC-4097
		SCALE	N/A
		REV	01
DO NOT SCALE DRAWING			
SHEET 2 OF 3			

# RECOMMENDED LAND PATTERN DIMENSIONS



SYMBOL	MIN	NOM	MAX
X	.35	.40	.45

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
	01	ADD "GREEN" BBG NOMENCLATURE	10/20/04	TU VU

<small>UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS DECIMAL XX ±0.10 XXX ±0.05 XXXX ±0.03</small>		<small>ANGULAR ±1°</small>	
APPROVALS	DATE	<b>IDT</b> Integrated Device Technology, Inc. www.IDT.com (408) 727-6116 FAX (408) 492-8074	
DRAWN <i>dy/p</i>	10/23/00	TITLE: <b>BB/BBG 208 PACKAGE OUTLINE</b>	
CHECKED		DRAWING No. <b>PSC-4097</b>	
		SIZE	SCALE
		C	N/A
			REV
			01
DO NOT SCALE DRAWING			
SHEET 3 OF 3			